<u>onsemi</u>,

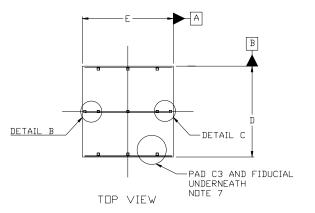
ODCSP8 3.16x3.16x0.64 CASE 570CS

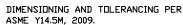
NDTES:

1.

ISSUE A

DATE 07 MAY 2019





- 2. CONTROLLING DIMENSION: MILLIMETERS
- 3. DATUM C, THE SEATING PLANE, IS DEFINED BY THE SPERICAL CROWNS OF THE CONTACT BALLS.
- 4. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE CONTACT BALLS.
- 5. DIMENSION & IS MEASURED AT THE MAXIMUM CONTACT BALL DIAMETER PARALLEL TO DATUM C.

-A3

A1-

6. DRIENTATION FIDUCIAL LOCATION. LOCATED BETWEEN PADS C2 AND C3.

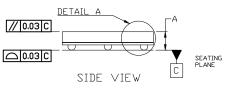
GLASS

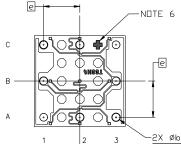
DETAIL A

A2-

SIPM CHIP

 REFERENCE ONLY, NO ACTUAL DRIENTATION FEATURE ON TOP. SEE DETAIL B AND C AT 10X MAGNIFICATION.





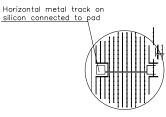
BOTTOM VIEW

-2X Øb **∲0.10@CAB** NDTE 5

Horizontal metal track on silicon not connected to pad

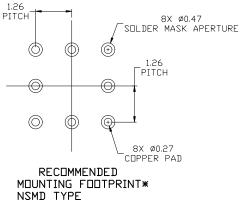


DETAIL C DRIENTATION DETAIL VIEW



DETAIL B DRIENTATION DETAIL VIEW

	MILLIMETERS			
DIM	MIN.	NDM.	MAX.	
Α	0.59	0.64	0.69	
A1	0.15	0.18	0.20	
A2	0.075	0.090	0.105	
A3	0.355	0.370	0.385	
ð	0.23	0.26	0.29	
D	3.11	3.16	3.21	
Е	3.11	3.16	3.21	
e	1.26 BSC			



For additional information on our Pb-Free strategy and soldering details, piease download the DN Seniconductor Soldering and Mounting Techniques Reference Manual, SDLDERRM/D.

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DESCRIPTION:	ODCSP8 3.16x3.16x0.64		PAGE 1 OF 1	
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